

previously added by the preliminary amendment mailed on 09/19/00,  
replace the paragraph therein with:

*B1*  
--This application claims the benefit of and is a  
continuation of Application No. 09/153,630, filed September  
15, 1998, now issued as U.S. Patent No. 6,153,829.--

Page 6, line 18, replace the paragraph beginning there at  
with:

*B2*  
--The bond pads 16 of the first bond shelf 18 are connected  
to a pair of power busses 24 and 26 within the package. The  
busses 24 and 26 are separated and located within the same  
horizontal plane of the package. By locating both power busses 24  
and 26 within the same plane the present invention provides a  
package that may require less layers than a package that has two  
power busses located within different layers of the package.--

Page 7, line 23, replace the paragraph beginning there at  
with:

*B3*  
--The different layers of bond pads 16, contacts 32 and  
busses 24 and 26, routing traces 28, and bus 30 may all be  
interconnected by vias 38. The busses 24 and 26 may include  
clearance spaces 42 that electrically isolate the busses 24 and 26  
from the vias 38. Additionally, the busses 24 and 26 are also  
separated by spaces 43.--

Page 8, line 1, replace the paragraph beginning there at  
with:

*B4 Cont.*  
Figure 4 shows a first conductive strip 44 and a second

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conductive strip 46 that wrap around an edge of the first bond shelf 18 to connect the bond pads 16 to the power busses 24 and 26. As shown in Figure 1, the conductive strips 44 and 46 connect to the power busses 24 and 26 at the edge of the first bond shelf 18. The conductive strips 44 and 46 can be separated by a pair of notches 48 formed in the first bond shelf 18. Some of the bond pads 16 are connected to bus 24 by conductive strip 44 while other bond pads 16 are connected to bus 26 by strip 46. The separate strips allow the bond pads 16 on the first shelf 18 to be connected to two different voltage levels. The other bond pads 16 on the first bond shelf 18 may be interconnected to other layers and/or contacts 34 by vias 38. --

Page 8, line 24, replace the paragraph beginning there at and continuing onto page 9 with:

Sub C27  
B5  
--The conductive strips 44 and 46 can be formed by initially masking off all surfaces of the package housing, except the edge of the first bond shelf 18 with a plating resist maskant 50, as shown in Figure 5. The masked housing can then be dipped into a plating bath 52 as shown in Figure 5. The plating bath 52 plates a conductive material such as copper onto the edge of the first bond shelf 18. The maskant 50 is then removed and the notches 48 can be drilled into the edges of the first bond shelf 18 to separate the plated material into the first and second conductive strips 44 and 46. All exposed copper surfaces may then be plated with gold. --

Page 9, line 9, replace the paragraph beginning there at with: